

PROCEEDINGS OF SPIE

Advanced Fabrication Technologies for Micro/Nano Optics and Photonics VII

Georg von Freymann
Winston V. Schoenfeld
Raymond C. Rumpf
Editors

3–5 February 2014
San Francisco, California, United States

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Nanoscribe GmbH (Germany)

Published by
SPIE

Volume 8974

Proceedings of SPIE 0277-786X, V. 8974

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Advanced Fabrication Technologies for Micro/Nano Optics and Photonics VII, edited by Georg von Freymann,
Winston V. Schoenfeld, Raymond C. Rumpf, Proc. of SPIE Vol. 8974, 897401 · © 2014 SPIE
CCC code: 0277-786X/14/\$18 · doi: 10.1117/12.2062957

Proc. of SPIE Vol. 8974 897401-1

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Author(s), "Title of Paper," in *Advanced Fabrication Technologies for Micro/Nano Optics and Photonics VII*, edited by Georg von Freymann, Winston V. Schoenfeld, Raymond C. Rumpf, Proceedings of SPIE Vol. 8974 (SPIE, Bellingham, WA, 2014) Article CID Number.

ISSN: 0277-786X
ISBN: 9780819498878

Published by
SPIE
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org

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Printed in the United States of America.

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